

RoHS

COMPLIANT

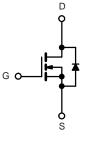
## N-Channel 60 V (D-S) Super Junction Power MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega) \qquad I_{D}(A)^{a}$				
60	0.0026 at V <sub>GS</sub> = 10 V	150			
60	0.0042 at V <sub>GS</sub> = 4.5 V	110			

#### TO-220 Pin Configuration



Top View



**FEATURES** 

• 175 °C Junction Temperature

• DT-Trench Power MOSFET

• Material categorization:

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T <sub>C</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Limit	Unit				
Gate-Source Voltage	V <sub>GS</sub>	± 20	V				
Continuous Drain Current /T 175 °C\b	T <sub>C</sub> = 25 °C	1-	150				
Continuous Drain Current (T <sub>J</sub> = 175 °C) <sup>b</sup>	T <sub>C</sub> = 100 °C	I <sub>D</sub>	110 <sup>a</sup>				
Pulsed Drain Current	I <sub>DM</sub>	600	A				
Continuous Source Current (Diode Conduction)	۱ <sub>S</sub>	150 <sup>a</sup>					
Avalanche Current	I <sub>AS</sub>	110					
Single Avalanche Energy (Duty Cycle $\leq$ 1 %)	E <sub>AS</sub>	750	mJ				
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	210	w			
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	'D	3.5 <sup>b</sup> , 9.2 <sup>b, c</sup>	vv			
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C				

THERMAL RESISTANCE RATINGS								
Parameter		Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient <sup>a</sup>	$t \le 10 \text{ sec}$	R <sub>thJA</sub>	13	18	°C/W			
Maximum Junction-to-Ambient*	Steady State	<b>1</b> thJA	35	45				
Maximum Junction-to-Case		R <sub>thJC</sub>	0.8	1.0				

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

c.  $t \leq 10$  s.

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SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static	-				·		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 V, I_{D} = 250 \mu A$	60			V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \ \mu A$	1		2.5	v	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 48 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50		
		$V_{DS} = 48 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 \text{ °C}$			250		
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	$V_{DS} = 5 V, V_{GS} = 10 V$	150			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0026	0.0032	Ω	
	D	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A, T <sub>J</sub> = 125 °C		0.0032	0.0041		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A, T <sub>J</sub> = 175 °C		0.0036	0.0048		
		V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.0042	0.0050		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 48 V, I <sub>D</sub> = 20 A		50		S	
Dynamic	•						
Input Capacitance	C <sub>iss</sub>			3950			
Output Capacitance	C <sub>oss</sub>	$V_{GS}$ = 0 V, $V_{DS}$ = 48 V, f = 1 MHz		670		pF	
Reverse Transfer Capacitance	C <sub>rss</sub>			23		1	
Total Gate Charge <sup>c</sup>	Qg			67	78	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 48$ V, $V_{GS} = 10$ V, $I_{D} = 20$ A		12			
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			8.5			
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			10	20		
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = 48 V, $R_{L}$ = 0.6 $\Omega$		5	15	ns	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ 20 A, $\text{V}_\text{GEN}$ = 10 V, $\text{R}_\text{g}$ = 2.5 $\Omega$		55	70		
Fall Time <sup>c</sup>	s <sup>c</sup> t <sub>f</sub>			12	20		
Source-Drain Diode Ratings and Cha	aracteristics (	T <sub>C</sub> = 25 °C)			·1		
Pulsed Current	I <sub>SM</sub>				150	А	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = 20 A, V <sub>GS</sub> = 0 V		1	1.2	V	
Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/µs		45	100	ns	

Notes:

a. For design aid only; not subject to production testing.

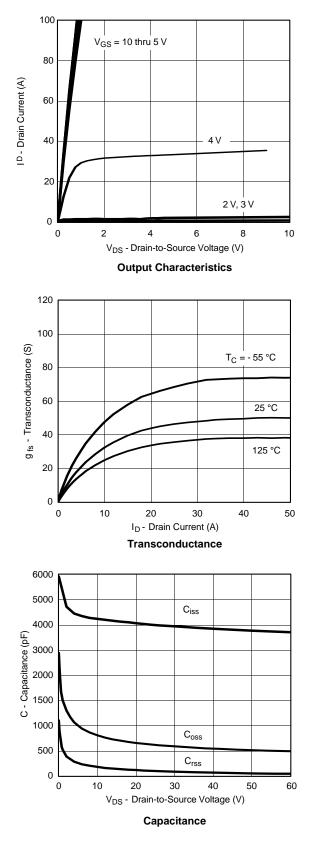
b. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

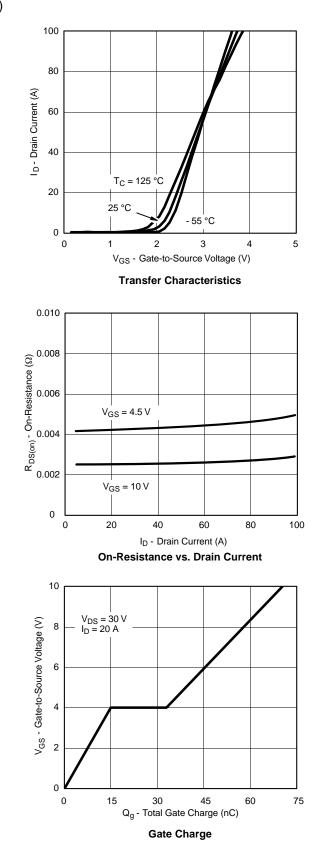
c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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#### TYPICAL CHARACTERISTICS (25 °C unless noted)

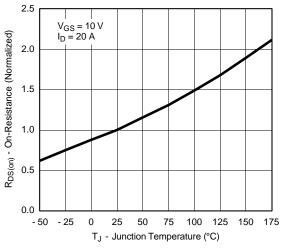




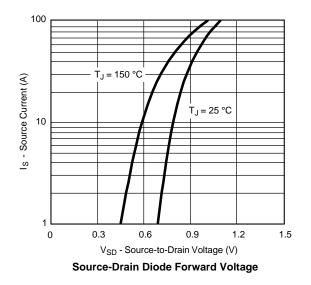
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#### TYPICAL CHARACTERISTICS (25 °C unless noted)



**On-Resistance vs. Junction Temperature** 

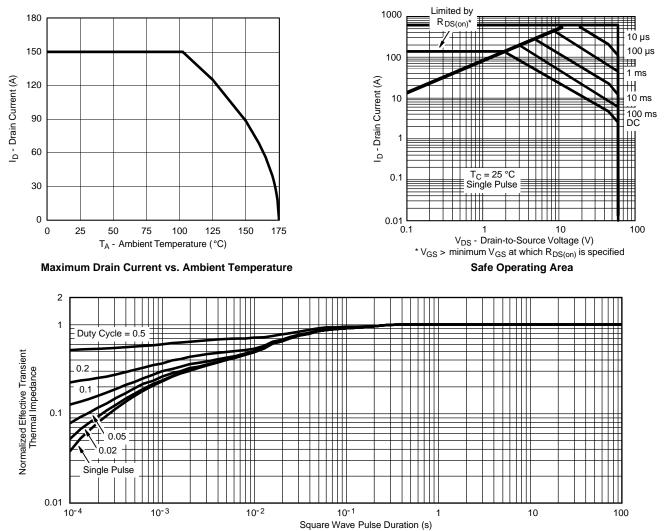




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#### **THERMAL RATINGS**

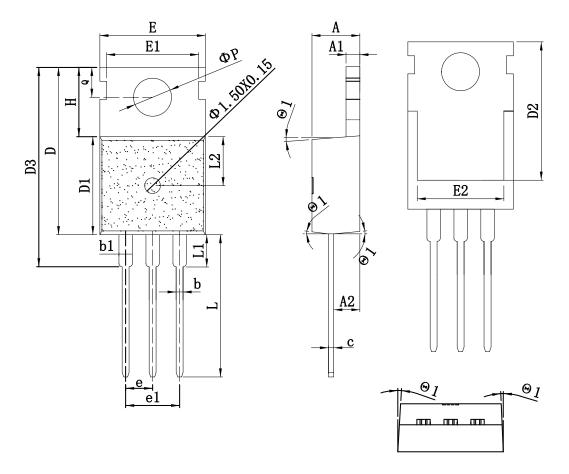


Normalized Thermal Transient Impedance, Junction-to-Case



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## TO-220\_3L-A PACKAGE OUTLINE

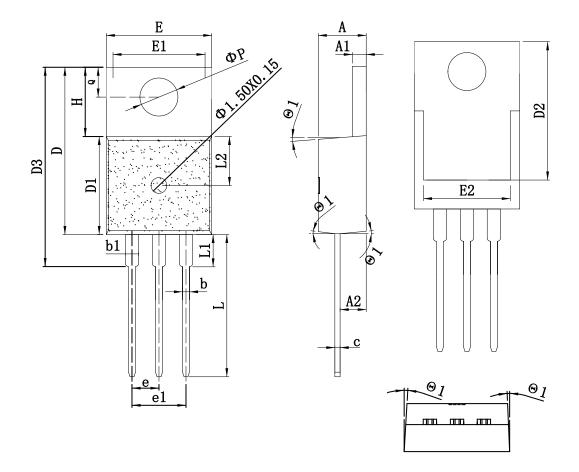


#### COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL		mm		SYMBOL	MROI MM			
SIMBOL	MIN	TYP	MAX	SIMBOL	MIN	TYP	MAX	
А	4.15	4.50	4.80	E1	8.25	8.70	9.15	
A1	1.15	1.30	1.50	E2	7.20	8.00	8.80	
A2	2.10	2.40	2.65	e	2.38	2.54	2.74	
b	0.65	0.80	1.00	e1	5.08REF			
b1	1.10	1.33	1.80	Н	6.20	6.50	6.90	
с	0.35	0.50	0.65	L	12.75	13.28	13.70	
D	14.25	15.75	16.15	L1	-	-	3.50	
D1	8.70	9.20	9.60	L2	2.30	4.65	7.00	
D2	12.30	13.10	13.85	φP	3.40	3.65	3.85	
D3	16.20	18.80	20.60	Q	2.50	2.80	3.00	
Е	8.68	10.02	11.00	θ	2°	-	7°	



## TO-220\_3L-B PACKAGE OUTLINE



#### COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL		mm		SYMDOL	SYMBOL mm		
SIMBOL	MIN	TYP	MAX	SIMBOL	MIN	TYP	MAX
А	4.15	4.50	4.80	E1	8.25	8.70	9.15
A1	1.15	1.30	1.50	E2	7.20	8.00	8.80
A2	2.10	2.40	2.65	e	2.38	2.54	2.74
b	0.65	0.80	1.00	e1	5.08REF		
b1	1.10	1.33	1.80	Н	6.20	6.50	6.90
с	0.35	0.50	0.65	L	12.75	13.28	13.70
D	14.25	15.75	16.15	L1	-	-	3.50
D1	8.70	9.20	9.60	L2	2.30	4.65	7.00
D2	12.30	13.10	13.85	φP	3.40	3.65	3.85
D3	16.20	18.80	20.60	Q	2.50	2.80	3.00
Е	8.68	10.02	11.00	θ	2°	-	7°



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